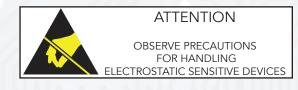
TOP LED - 3014 - COOL WHITE

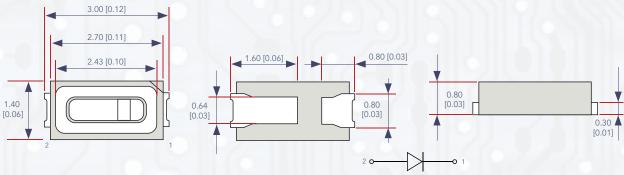
- CC - WMMI3014DS - HH - F -

FEATURES

- Viewing angle: 120 deg
- The materials of the LED dice is InGaN
- 3.0mm x 1.4mm x 0.80mm
- RoHS compliant led-free soldering compatible



PACKAGE OUTLINE



- All dimensions are in millimeters (inches)
- Tolerances are ±0.2mm (0.008 inch) unless otherwise noted

■ ABSOLUTE MAXIMUM RATINGS AT Ta - 25°C

PARAMETER	SYMBOL	VALUE	UNIT
Forward Current	If	40	mA
Reverse Voltage	Vr	5	V
Operating Temperature Range	Тор	-20 ~ +85	°C
Storage Temperature Range	Tstg	-35 ~ +85	°C
Pulse Foward Current	lfp	100	mA
Electrostatic Discharge	ESD	1000 (HBM)	V

■ ELECTRO-OPTICAL CHARACTERISTICS AT Ta - 25°C

PARAMETER		TEST CONDITION	0.44501	VALUE			=
		TEST CONDITION	SYMBOL	MIN	TYPE	MAX	UNIT
	Rank G1			2.8	- "	2.9	V
	Rank G2			2.9	11-0	3.0	
	Rank H1			3.0	-	3.1	
Forward Voltage	Rank H2	If - 30mA	Vf	3.1	-	3.2	
	Rank I1		3	3.2	-	3.3	
	Rank I2			3.3	-	3.4	
	Rank J1			3.4	-	3.5	
	Rank OBO		lv	3500	-	3850	mcd
Luminous Intensity	Rank OCO	If - 30mA		3850	1.7	4300	
	Rank ODO			4300	11	4750	
Luminou	us Flux	If - 30mA	Ø	- 1	12	-	lm
Viewing Angle at 50% lv		If - 30mA	2θ 1/2	-	120		Deg
Color Rending Index		If - 30mA	CRI	70	11-1	- 1	-
Reverse Current		Vr - 5V	lr	-	-	10	μΑ



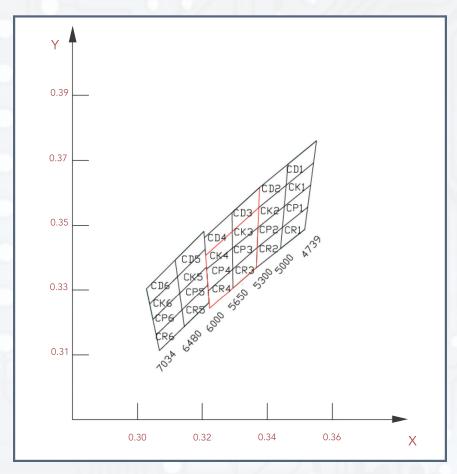
(Tolerance: Iv $\pm 10\%$, Vf ± 0.05 V, X, Y ± 0.005) IFP Conditions: Pulse Width ≤ 10 m sec. and Duty $\leq 1/10$.





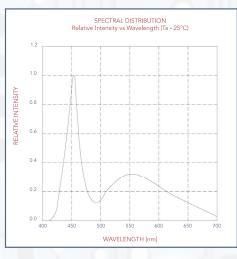


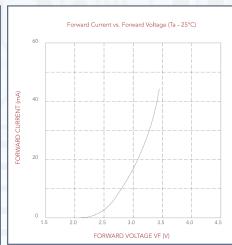
CHROMATICITY BIN

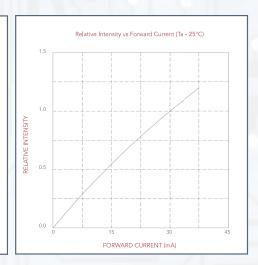


BIN CODE	CIE-X1	CIE-Y1	CIE-X2	CIE-Y2	CIE-X3	CIE-Y3	CIE-X4	CIE-Y4
CK3	0.3292	0.3481	0.3374	0.3554	0.3371	0.3493	0.3293	0.3423
CK4	0.3210	0.3407	0.3292	0.3481	0.3293	0.3423	0.3214	0.3352
CP3	0.3293	0.3423	0.3371	0.3493	0.3369	0.3431	0.3293	0.3364
CP4	0.3214	0.3352	0.3293	0.3423	0.3293	0.3364	0.3218	0.3298
CR3	0.3293	0.3364	0.3369	0.3431	0.3366	0.3369	0.3294	0.3306
CR4	0.3218	0.3298	0.3293	0.3364	0.3294	0.3306	0.3222	0.3243

■ TYPICAL OPTICAL CHARACTERISTICS CURVES



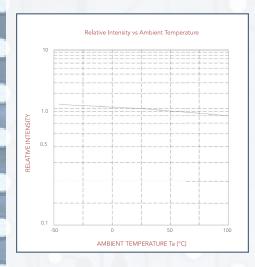


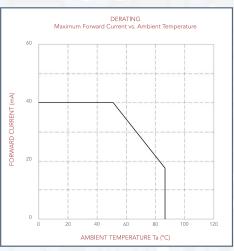


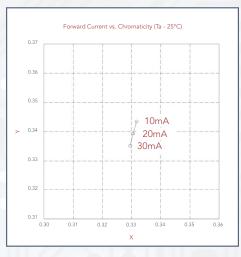


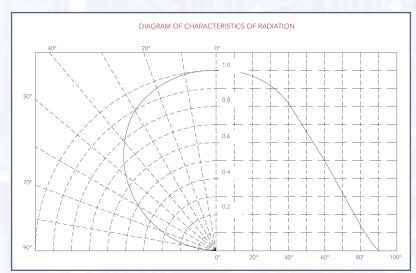


TYPICAL OPTICAL CHARACTERISTICS CURVES









- Soldering Condition

Recommended Soldering

After reflow soldering rapid cooling should be avoided

R	REFLOW SOLDERING		HAND SOLDERING
Pre-Heat	160°C ~ 180°C	Temperature	300°C Max
Pre-Heat Time	120 Seconds Max.	Soldering Time	3 Second Max - One Time Only
Peak Temperature	260°C Max		
Soldering Time	10 Seconds Max		
Condition	Refer to Temperature-profile		



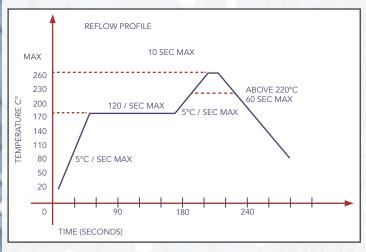


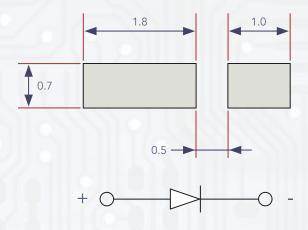
■ REFLOW PROFILE

- Temperature - profile (surface of circuit board)

Use the following conditions shown in the figure

- Recommend Pad Design (Units: mm)





Reflow soldering should not be done more than two times When soldering, do not put stress on the LEDs during heating

- Soldering Iron

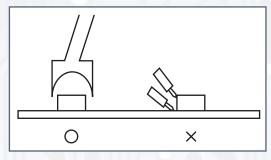
When hand soldering, keep the temperature of the iron under 300°C, and at that temperature keep the time under 3 sec.

The hand soldering should be done only a time

The basic spec is ≤5 sec. when the temperature of 260°C, do not contact the resin when hand soldering.

- Rework

Customer must finish rework within 5 sec under 260°C The head of iron can not touch the resin Twin-head type is preferred



- CAUTIONS

The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when using the picking up nozzle, the pressure on the silicone resin should be proper.





■ RELIABILITY

- TEST ITEMS AND RESULTS

TYPE	TEST ITEM	REF STANDARD	TEST CONDITIONS	NOTE	NUMBER OF DAMAGED
	Resistance to Soldering Heat (Reflow Soldering) JESD22 - B106		Tsld - 260°C, 10 sec	2 times	0/22
Environmental Sequence	Temperature Cycle	JESD22 - A104	-40°C 30 min ↑ 5 min 100°C 30 min	300 cycle	0/22
	Thermal Shock	JESD22 - A106	-40°C 15min ↑↓ 100°C 15 min	300 cycle	0/22
	High Temperature Storage	JESD22 - A103	T _a - 100°C	1000 hrs	0/22
	Low Temperature Storage	JESD22 - A119	T _a - 40°C	1000 hrs	0/22
Operation Sequence	Life Test	JESD22 - A108	T _a - 25°C I _F - 30mA	1000 hrs	0/22
	High Humidity Heat Life Test	JESD22 - A101	60°C RH-90% I _F - 30mA	1000 hrs	0/22

- CRITERIA FOR JUDGING THE DAMAGE

ITEM	CVMDOL	TECT CONDITIONS	CRITERIA FOR JUDGEMENT		
	SYMBOL	TEST CONDITIONS	MIN.	MAX.	
Forward Voltage	VF	IF- 30mA		U.S.L *) x 1.1	
Reverse Current	IR	VR - 5V		U.S.L*) x 2.0	
Luminous Intensity	IV	IF - 30mA	L.S.L**) x 0.7	-	

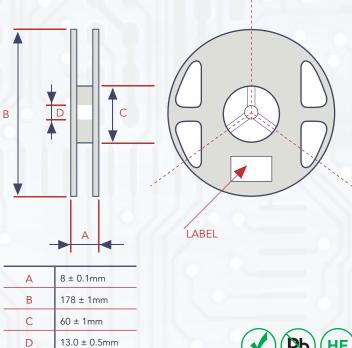
⁻ U.S.L.: Upper Standard Level - L.S.L.: Lower Standard Level

PACKAGING SPECIFICATIONS

- Feeding Direction



- Dimensions of Reel (Unit: mm)









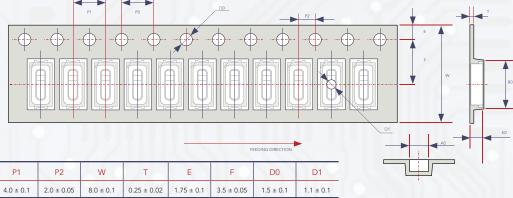
■ PACKAGING SPECIFICATIONS - Dimensions of Tape (Unit: mm)

K0

 1.4 ± 0.1

 4.0 ± 0.1





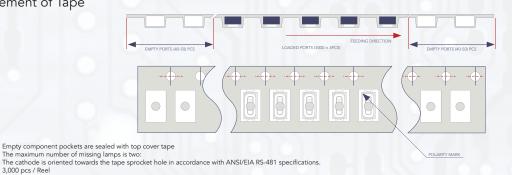
Arrangement of Tape

3,000 pcs / Reel

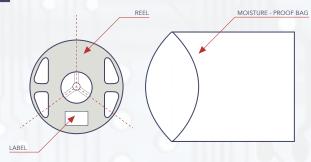
 $3.3. \pm 0.1$

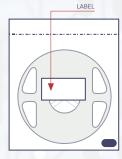
Α0

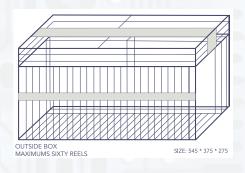
 1.6 ± 0.1



PACKAGING SPECIFICATIONS







Label

NOTE:



Cautions

- Packaging Specification

- Reeled products (3,000 pcs) packed in a sealed moisture-proof bags along with a desiccant. Eighty moisture proof bags maximum are put the outside box (size: about 545mm x about 375mm x about 275mm) . Together with buffer material, and it is packed. (Pare No., Lot No., quantity should appear on the label on the moisture-proof bag, part No. And quantity should appear on the label on the cardboard box.) The number of the loading steps of outside the box (cardboard box) has two steps.

Storage Conditions

- Before Opening the Packge - The LEDs should be kept at 30°C or less and 70% RH or less. The LEDs should be used within a year. When storing the LEDs, moisture proof packaging with absorbant material (silica gel) is recommended.

- After Opening the Packge - The LEDs should be kept at 30°C or less and 50% RH or less. If unused LEDS remain, they should be stored in moisture proof packages, such as sealed containers with packages of moisture absorbent material (silica gel). It is also recommended to return the LEDs to the original moisture proof bag and to reseal the moisture proof bag again.





